

A cross-sectional diagram of a semiconductor device assembly, labeled 100. The assembly includes a substrate 102 at the base. A central vertical structure 108 is surrounded by a frame-like component 110. Various layers and components are labeled: 104, 106, 112, 114, 116, 118, 120, 122, 123, 124, 126, and 128. The diagram shows a complex arrangement of materials and structures, likely representing a multi-layered circuit or sensor array.

Fig. 1

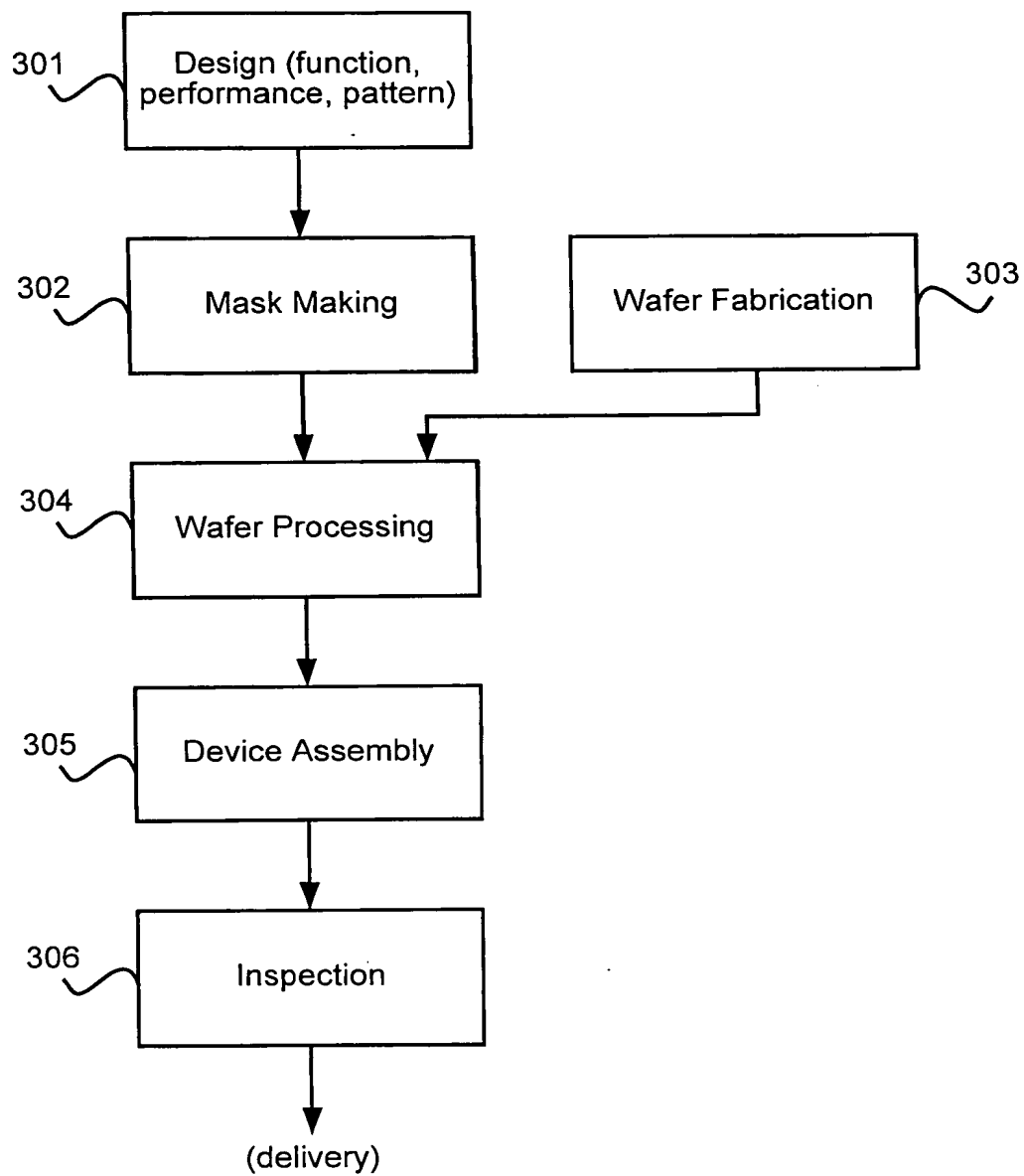
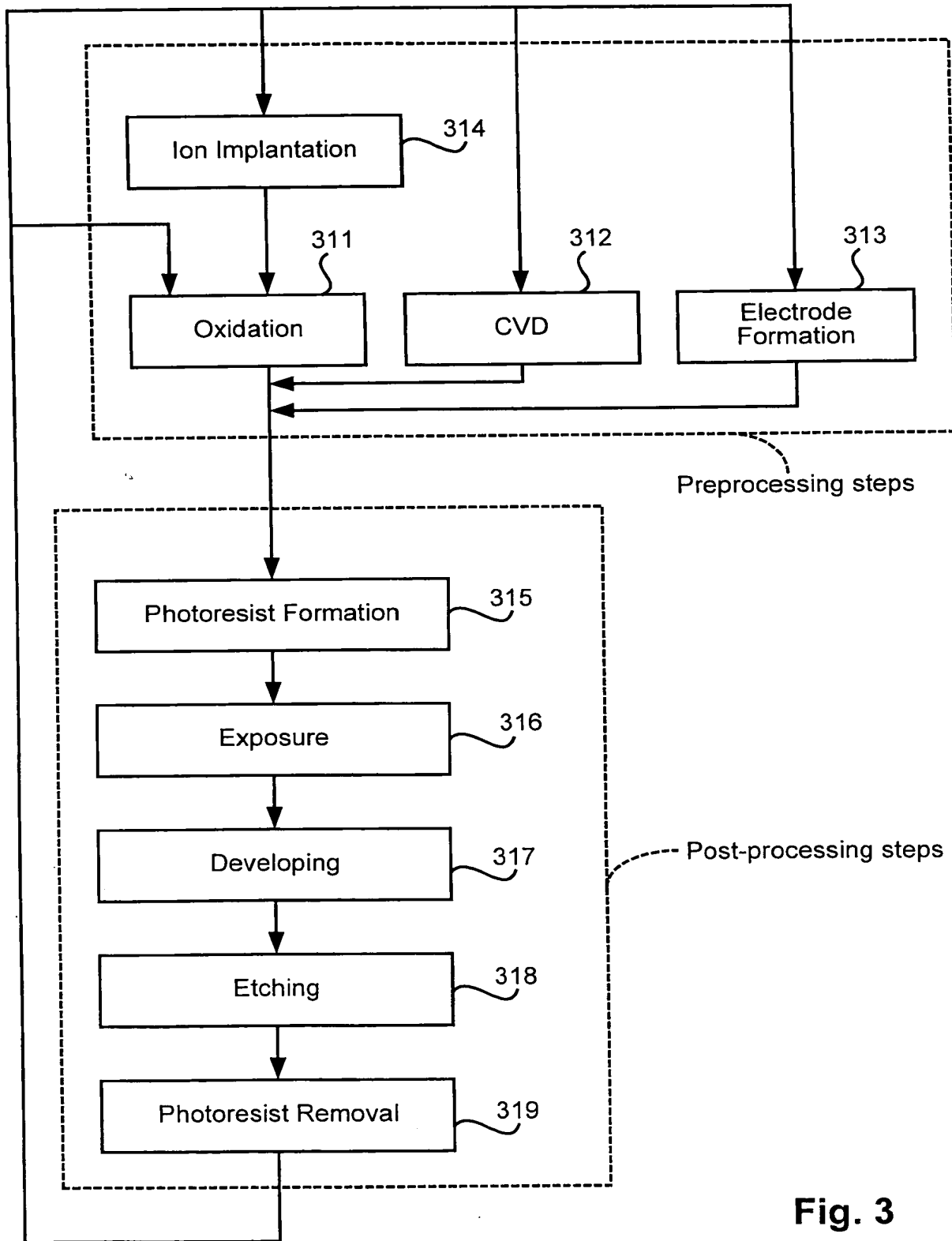


Fig. 2



**Fig. 3**

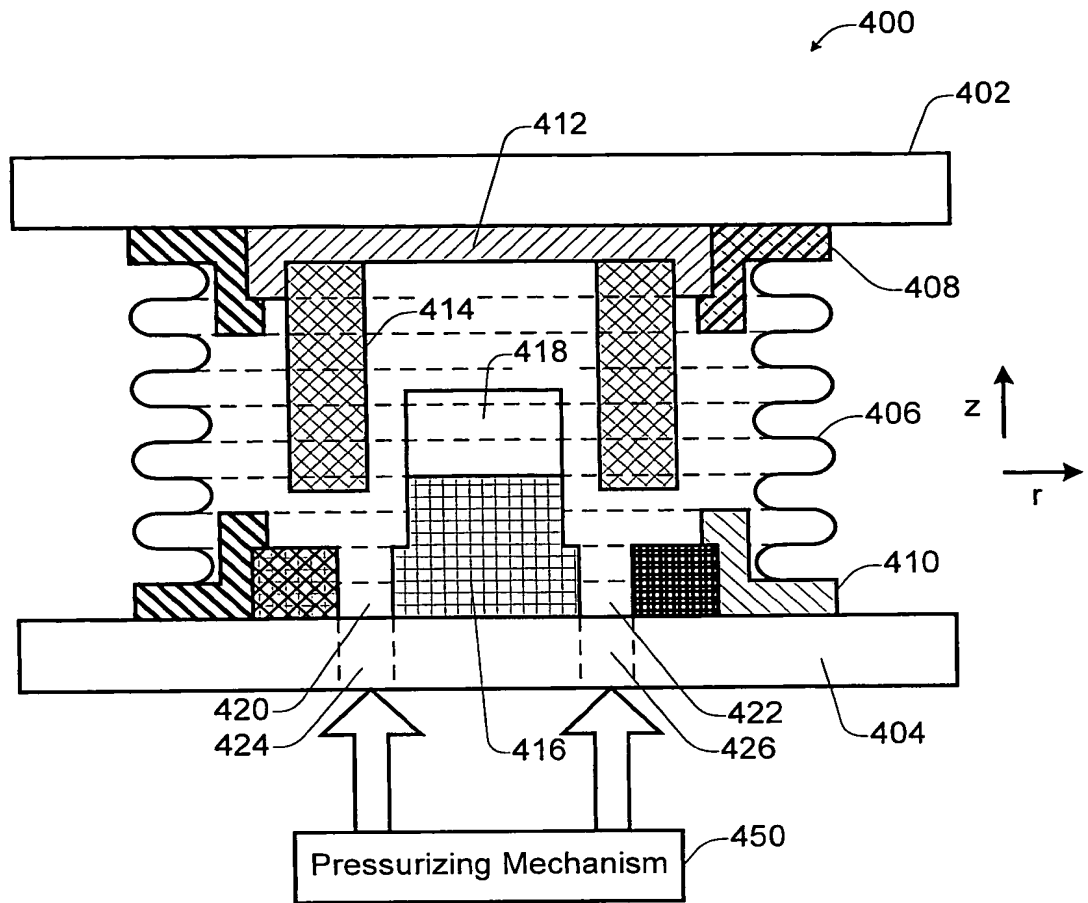


Fig. 4

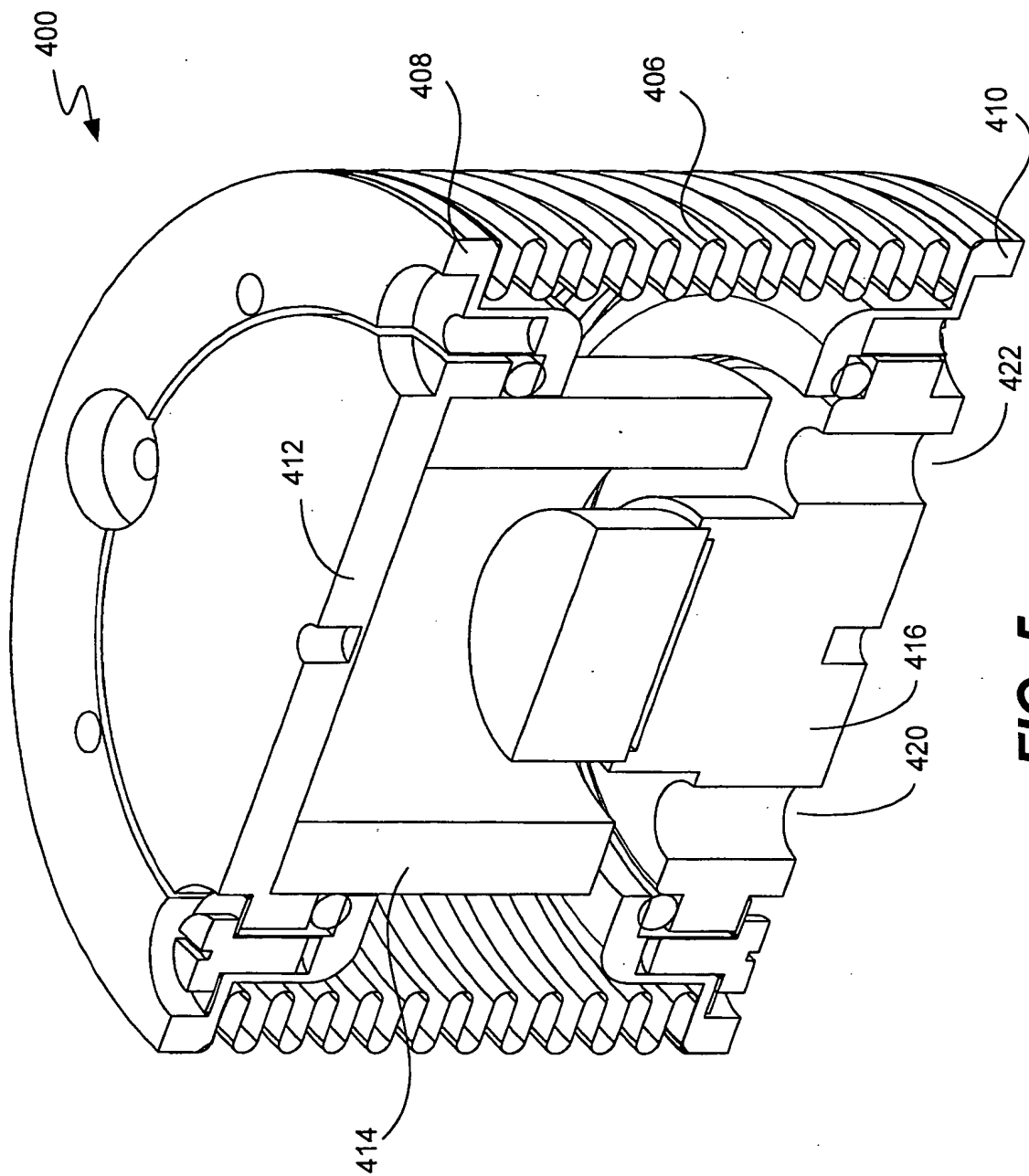
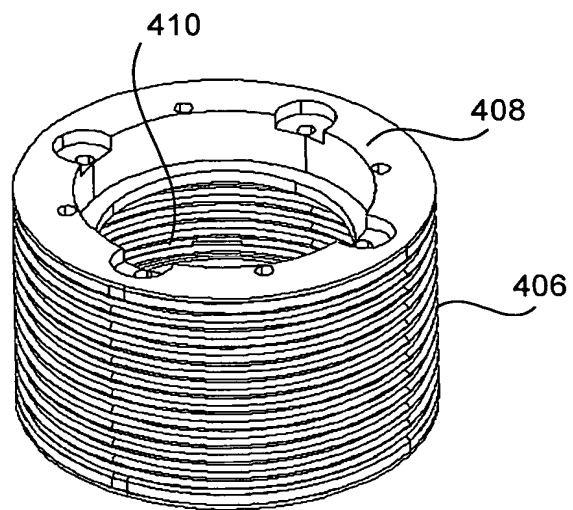
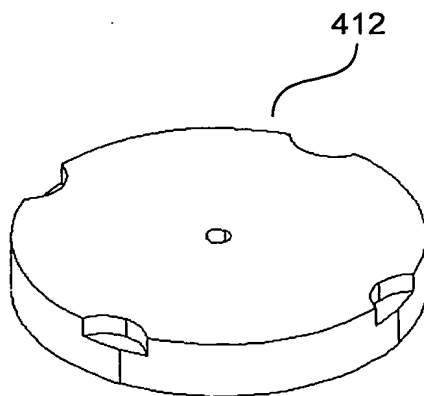


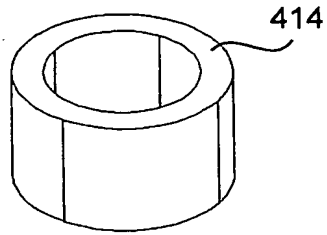
FIG. 5



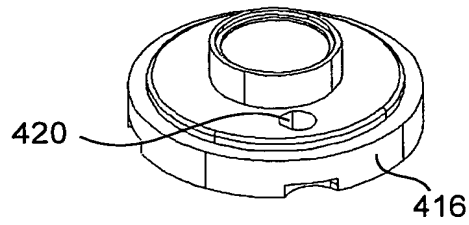
**FIG. 6**



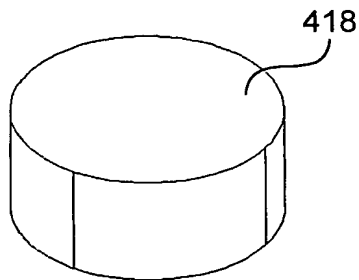
**FIG. 7**



**FIG. 8**



**FIG. 9**



**FIG. 10**

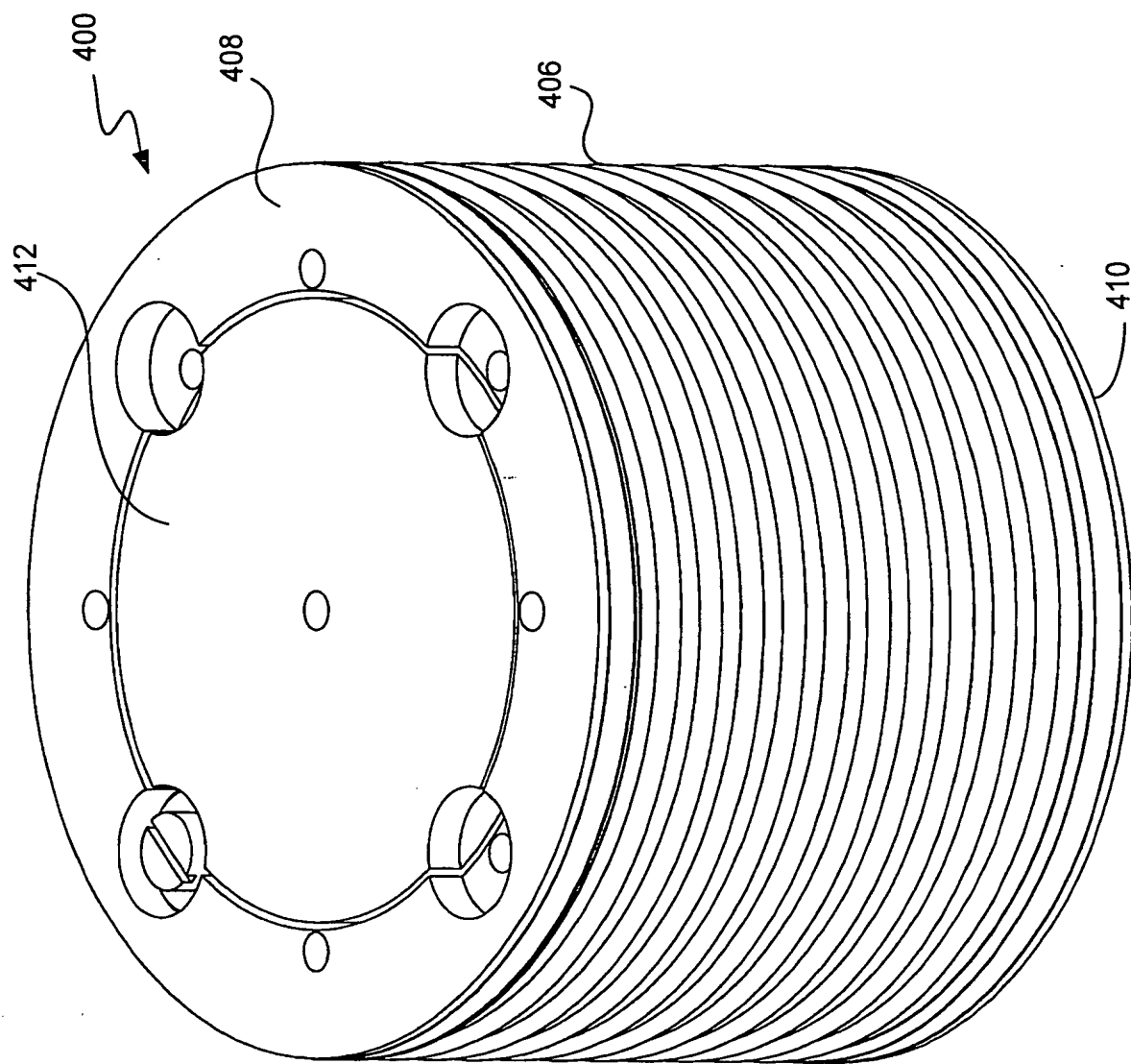


FIG. 11



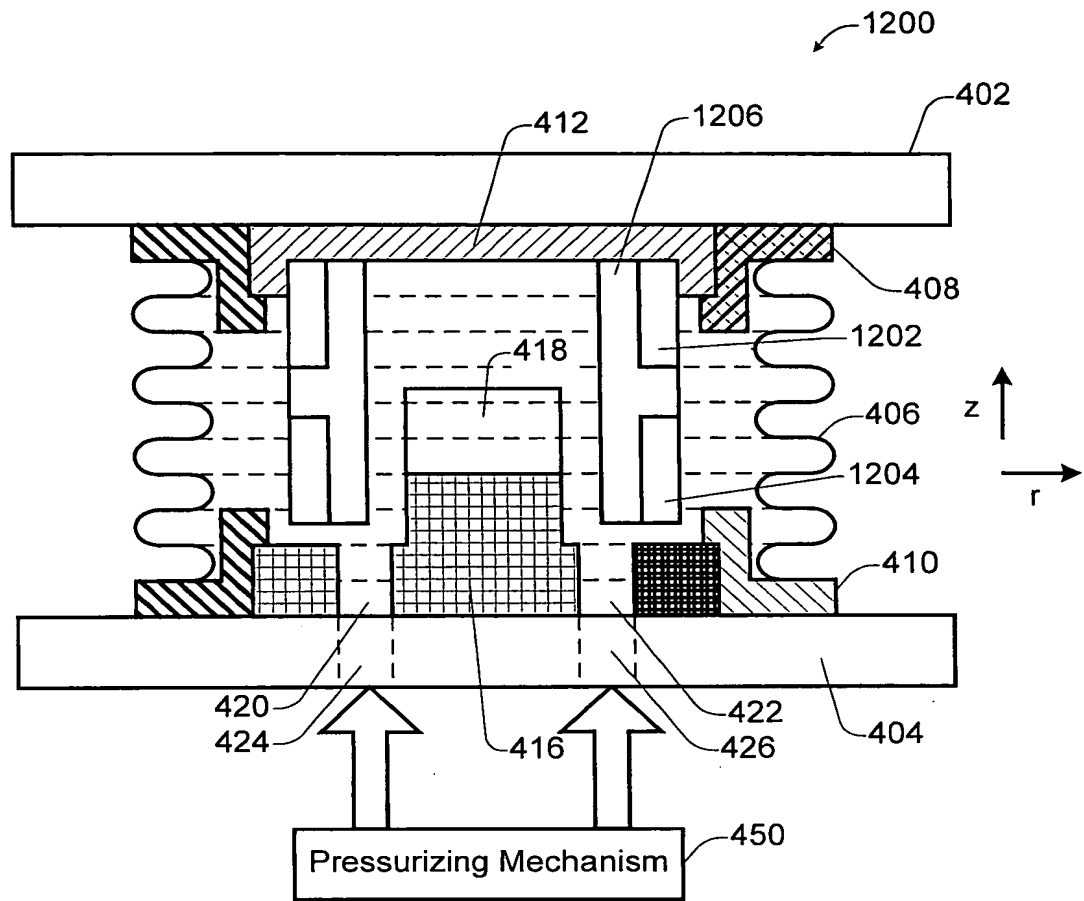
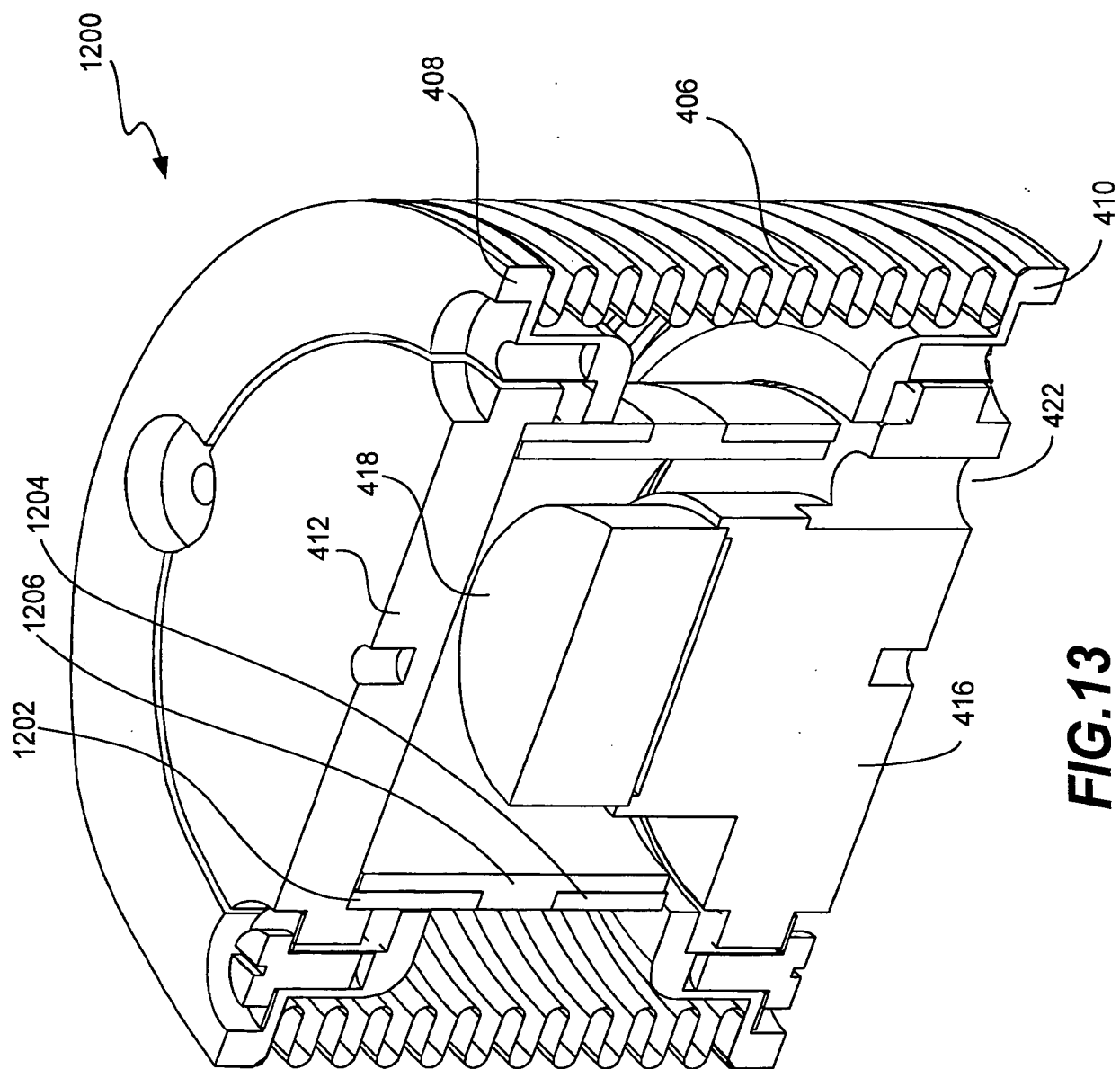


Fig. 12



**FIG. 13**

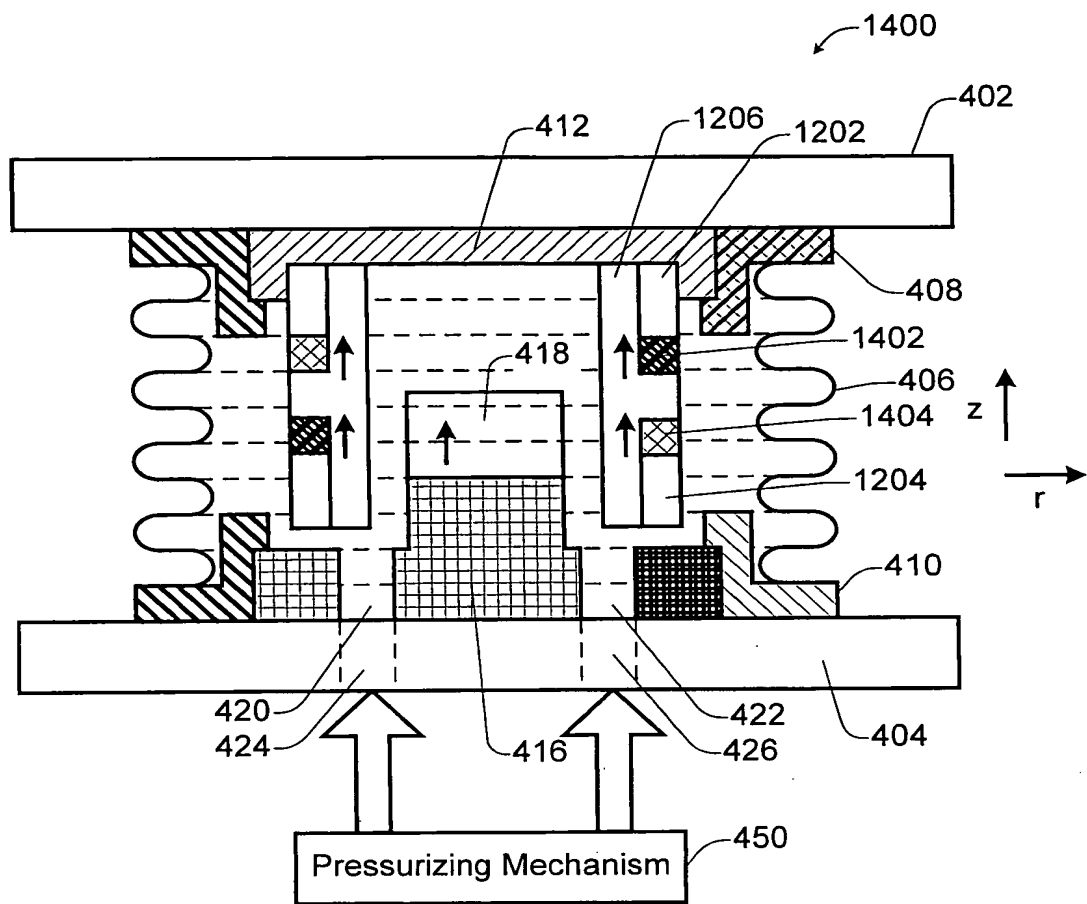


Fig. 14

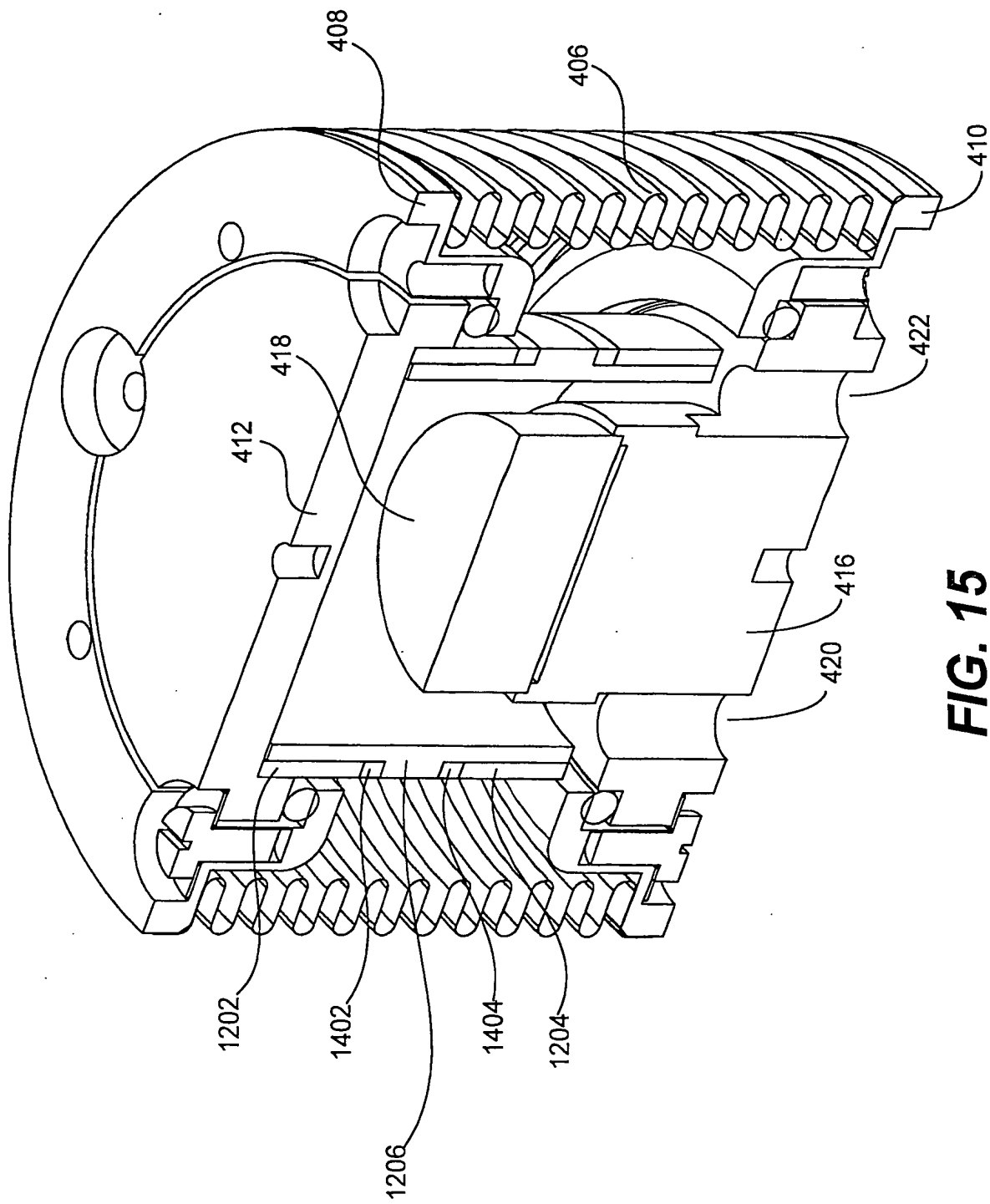
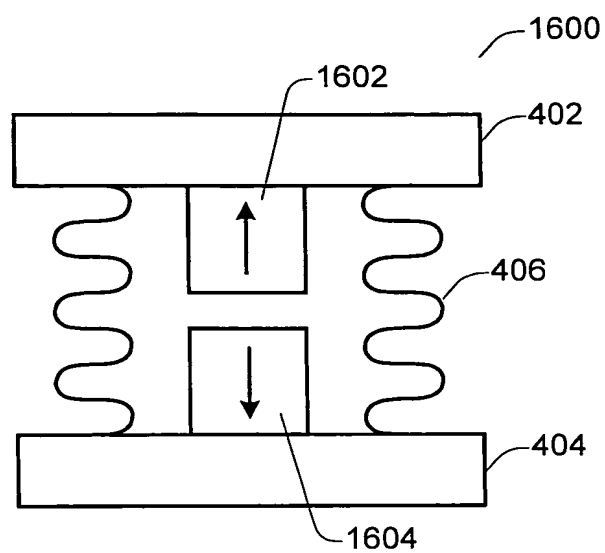
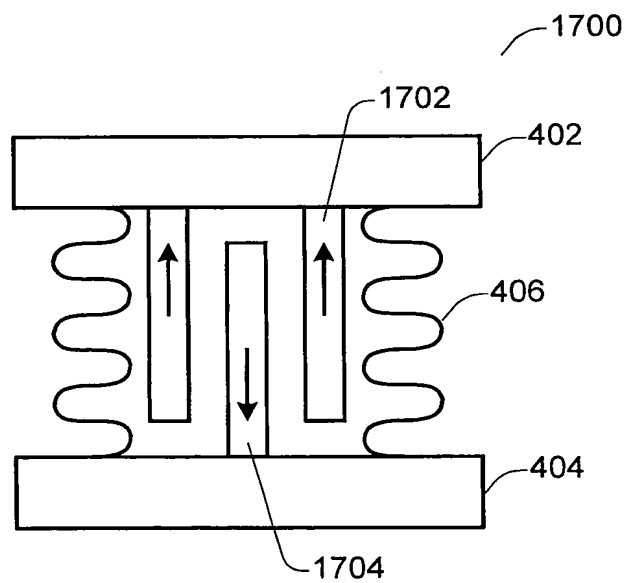


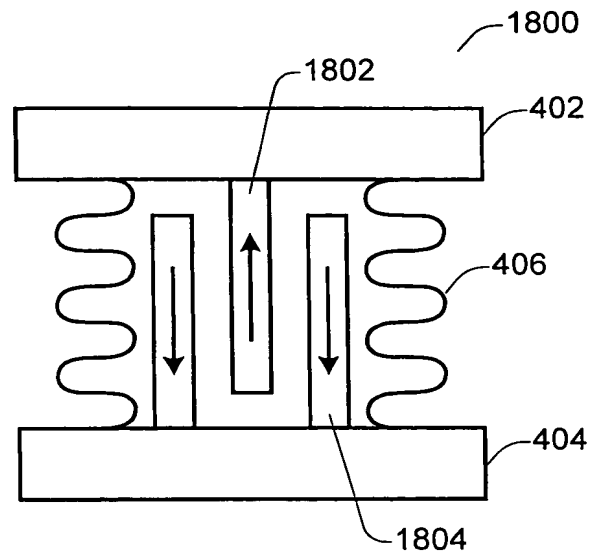
FIG. 15



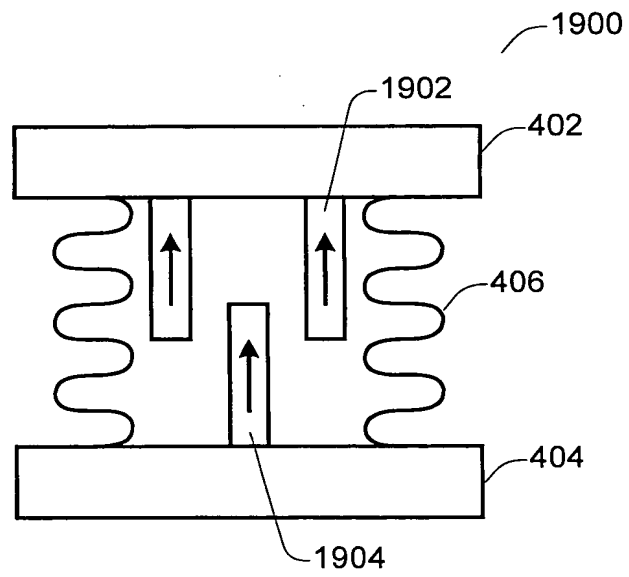
**Fig. 16**



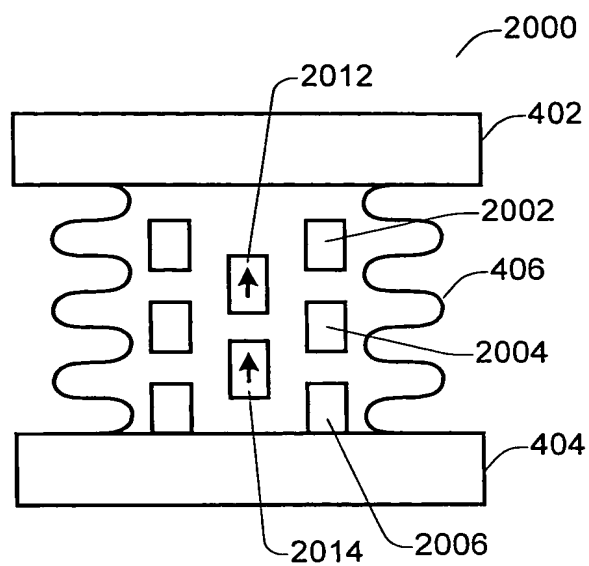
**Fig. 17**



**Fig. 18**



**Fig. 19**



**Fig. 20**

